

Bill of Materials

TI DESIGNS

QTY	Nomenclature	Value	Package	MFG	Recommended PN	MFG
1	C1	0.1 uF	0603	TDK	C1608X7R1E104K	
1	C2	0.47 uF	0603	TDK	C1608Y5V1E474Z	
1	C3	1 uF	0603	TDK	C1608Y5V1A105Z	
DNP	C4	DNP	0603			
1	C5	39pF	0603	TDK	C1608C0G1H390J	
1	C8	0.01uF	0603	TDK	C1608X7R1H103K	
2	R1, R2	4.7K ohms	0402	Panasonic	ERJ-2GEJ472X	
DNP	R10, R11	10K ohms	0402	Panasonic	ERJ-2GEJ103X	
8	R3, R4, R5, R6, R7, R9, R8, R	0 ohms	0402	Panasonic	ERJ-2GE0R00X	
DNP	Q1	NPN transistor	SOT-23	ON Semi	MMBT3904LT3G	
2	RF1, RF2	SFM-110-02-L-D-A	CON_SMVT_2x10_50_F_SFM_FLIP_C	Samtec	SFM-110-02-L-D-A	
1	U1	RF430CL330H	TSSOP (PW) 14 pin	Texas Instruments	RF430CL330H	

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